



Discription

The HCESD0603NC3V3B-M protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events.

Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



DFN0603-2L

Features

- ★ Small Body Outline Dimensions:
0.61 mm x 0.31 mm
- ★ Low Body Height: 0.28 mm
- ★ Low Leakage
- ★ Response Time is Typically < 1 ns
- ★ ESD Rating of Class 3 per Human Body Model
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ These are Pb-Free Devices
- ★ We declare that the material of product compliance with RoHS requirements and Halogen Free.



Circuit Diagram

Ordering information

Product ID	Pack	Qty(PCS)
HCESD0603NC3V3B-M	DFN0603-2L	15000

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power (t _p = 8/20μs)	90	W
T _L	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +150	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
T _j	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD)	air discharge contact discharge	±25 ±20 KV



Electrical Characteristics

Device	V_{RWM} (V)	I_R (μ A) @ V_{RWM}	V_{BR} (V) @ I_T (Note 2)		I_T	V_C (V) @ $I_{PP} = 1$ A (Note 3)	V_C (V) @ MAX I_{PP} (Note 3)	I_{PF} (A) (Note 3)	P_{PK} (W) (Note 3)	C (pF)
	Max	Max	Min	Max	mA	Max	Max	Max	Max	Typ
HCESD0603NC3V3B-M	3.3	0.1	5.0	6.5	1.0	7	10	5	90	12

Other voltage available upon request.

- V_{BR} is measured with a pulse test current I_T at an ambient temperature of 25°C
- Surge current waveform per Figure 1.

Typical Characteristics

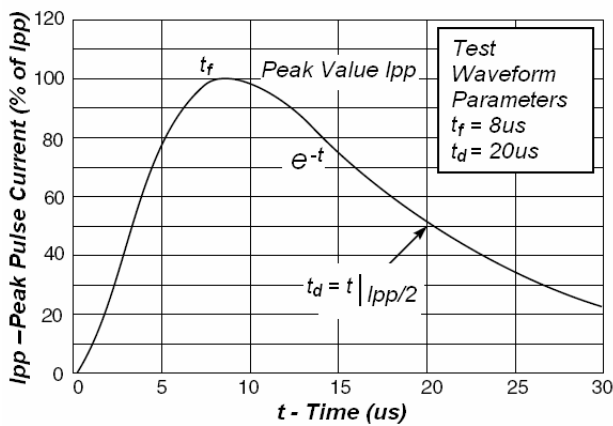


Fig1. Pulse Waveform

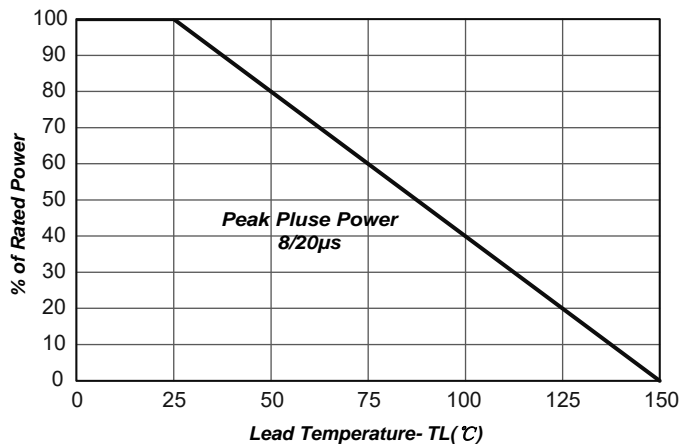


Fig2. Power Derating Curve

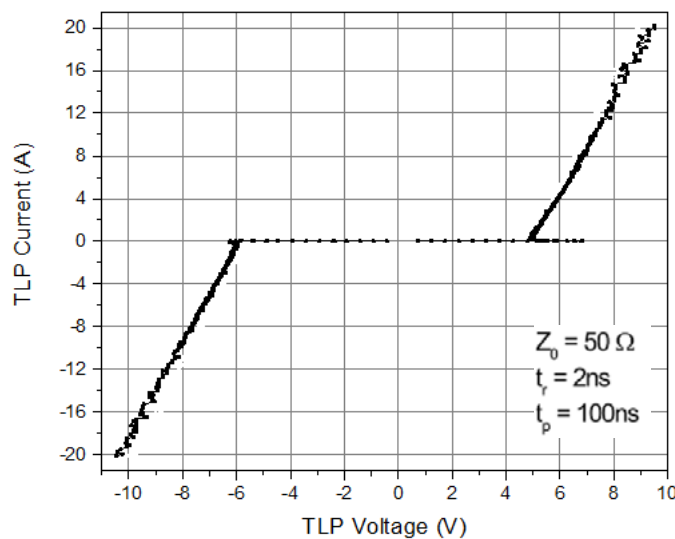
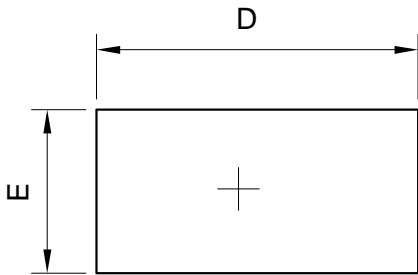


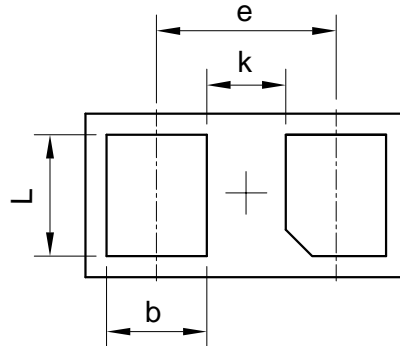
Fig3. TLP Measurement



Outline And Dimensions

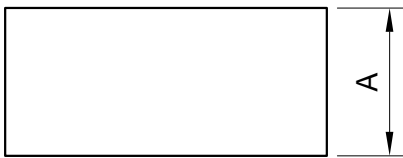


TOP VIEW



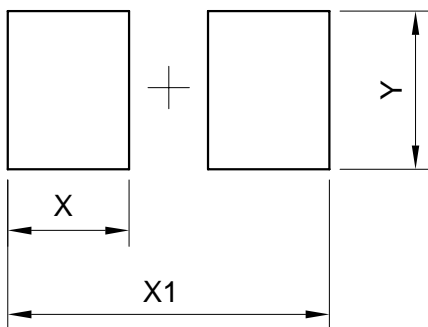
BOTTOM VIEW

DFN0603-2L			
Dim	Min	Typ.	Max
D	0.58	0.61	0.64
E	0.28	0.31	0.34
e	-	0.34	-
L	0.20	0.23	0.26
b	0.16	0.19	0.22
A	0.25	0.28	0.31
k	0.12	0.15	0.18
All Dimensions in mm			



SSIDE VIEW

Soldering Footprint



DFN0603-2L	
DIM	(mm)
X	0.23
X1	0.61
Y	0.30



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